



Egis Technology Inc.

2025Q1 Investor Conference

ir@egistec.com
2025.05.09



Egis Technology Group - Company Profile



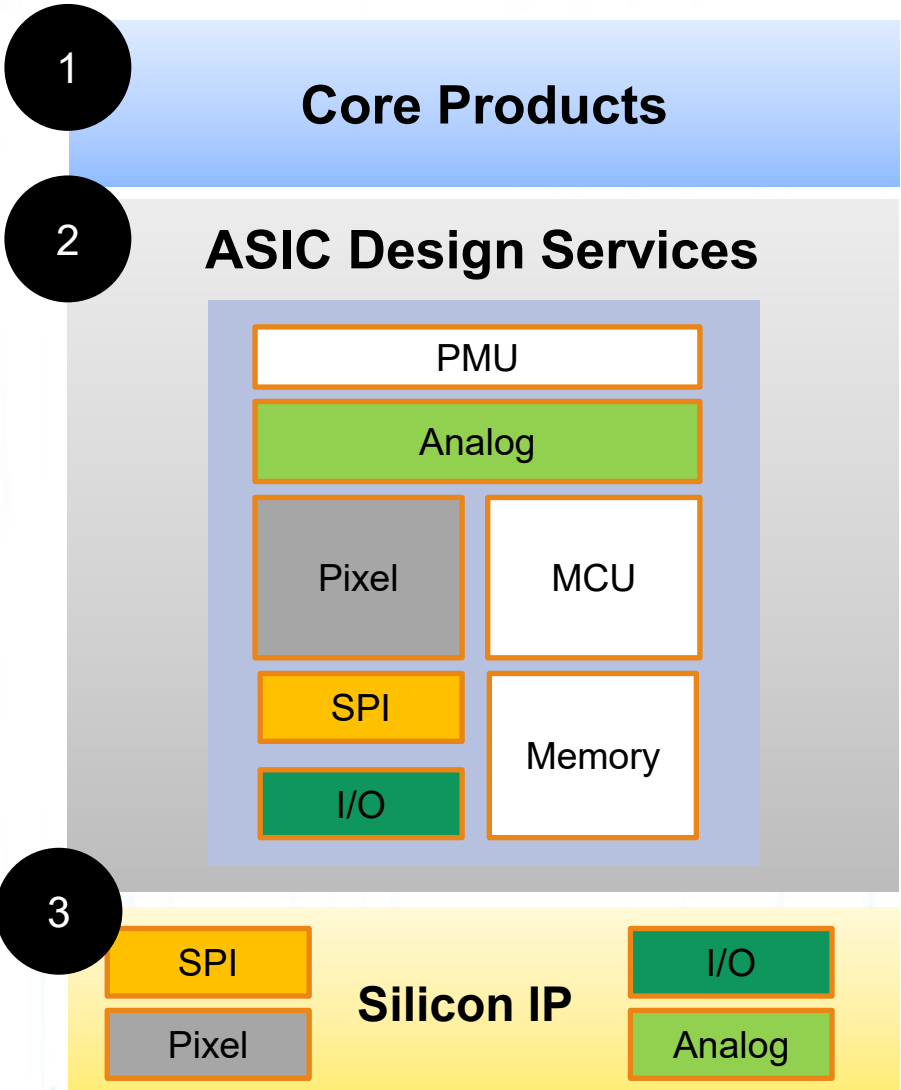
Established

Founded in 2007
Public Company since 2015
8 Public Companies as of 2024



Employees

1300+
(80% RD)





Patents

958 patents granted
431 patents pending

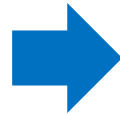
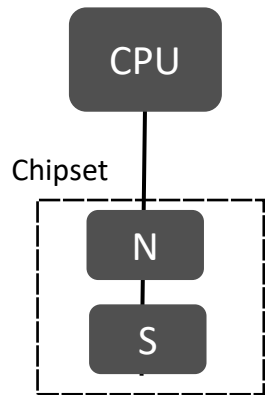


Offices

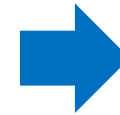
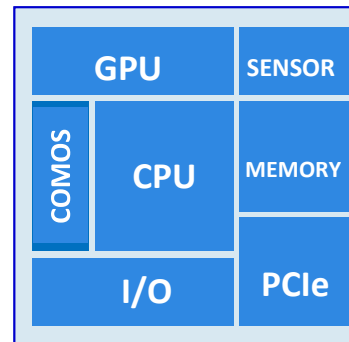
Taiwan (8), Korea (1),
Japan (5), and China (3)

The Evolution of Chips(IC Design)

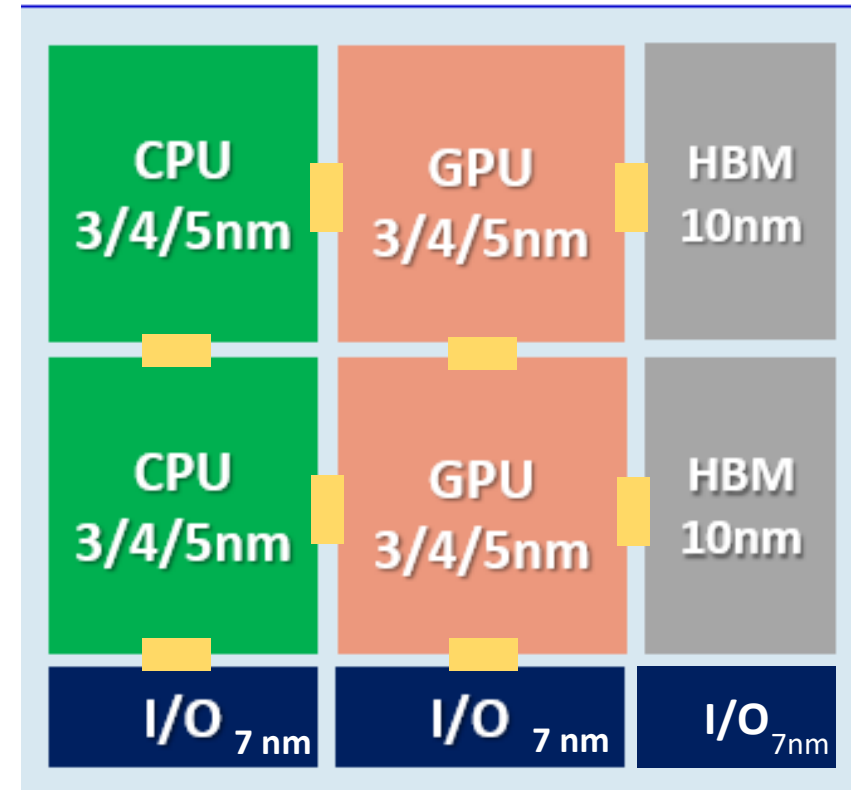
1.0 CPU + Chipset



2.0 SoC Single Die



3.0 ChipLet Multi-Die Design

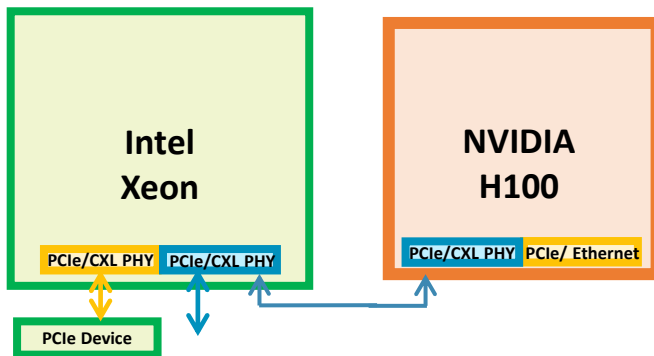


Moore's Law

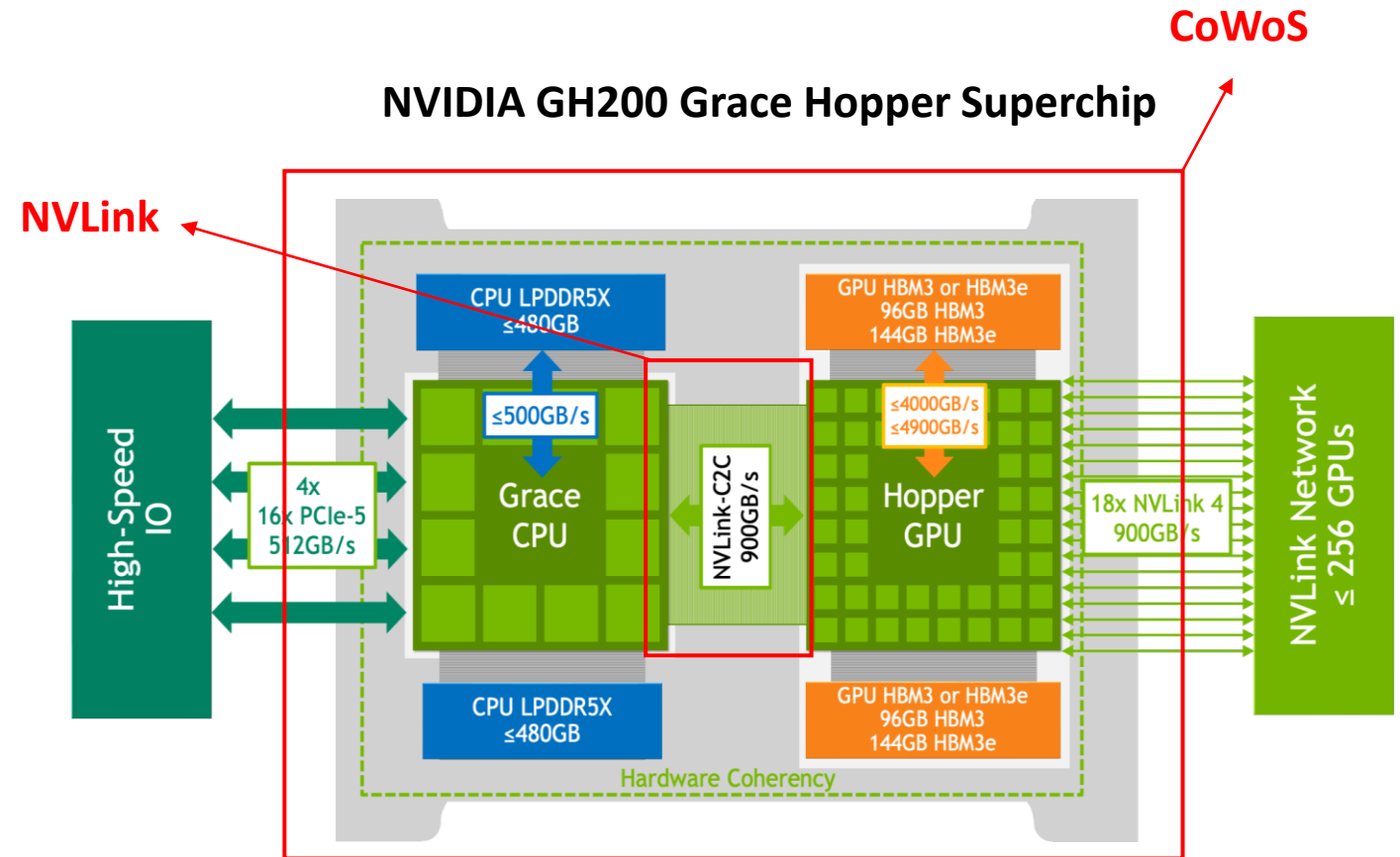
More than Moore

AI HPC Server Chiplet Architecture

Intel Xeon(CPU) + NVIDIA H100 (GPU)



NVIDIA GH200 Grace Hopper Superchip

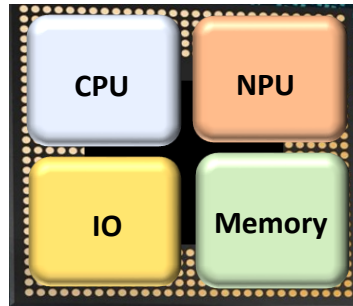


- NVLink vs PCIe Gen5 bandwidth >7X
Power consumption <20%

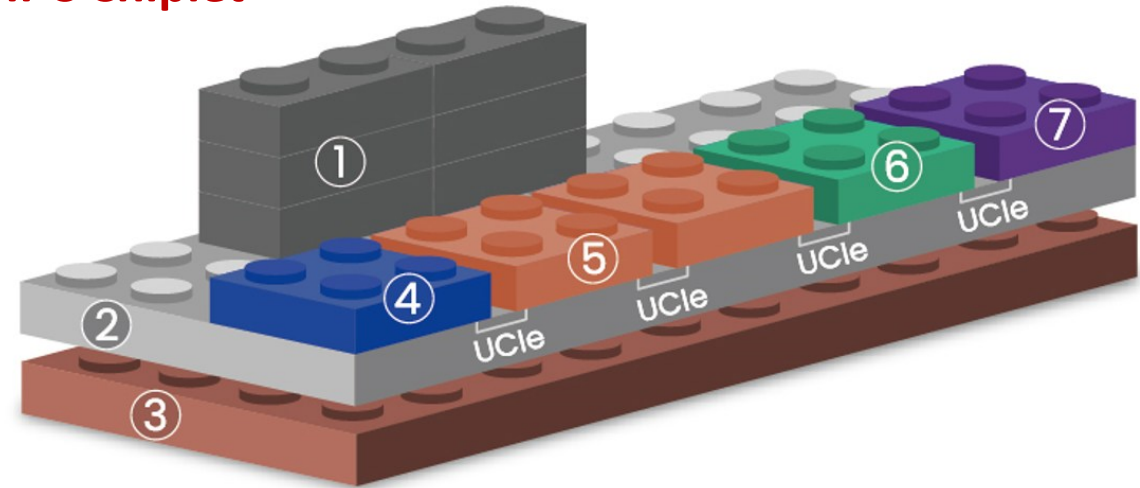
Design Service

From ASIC to Chiplet Architecture Solution

ASIC Design Service



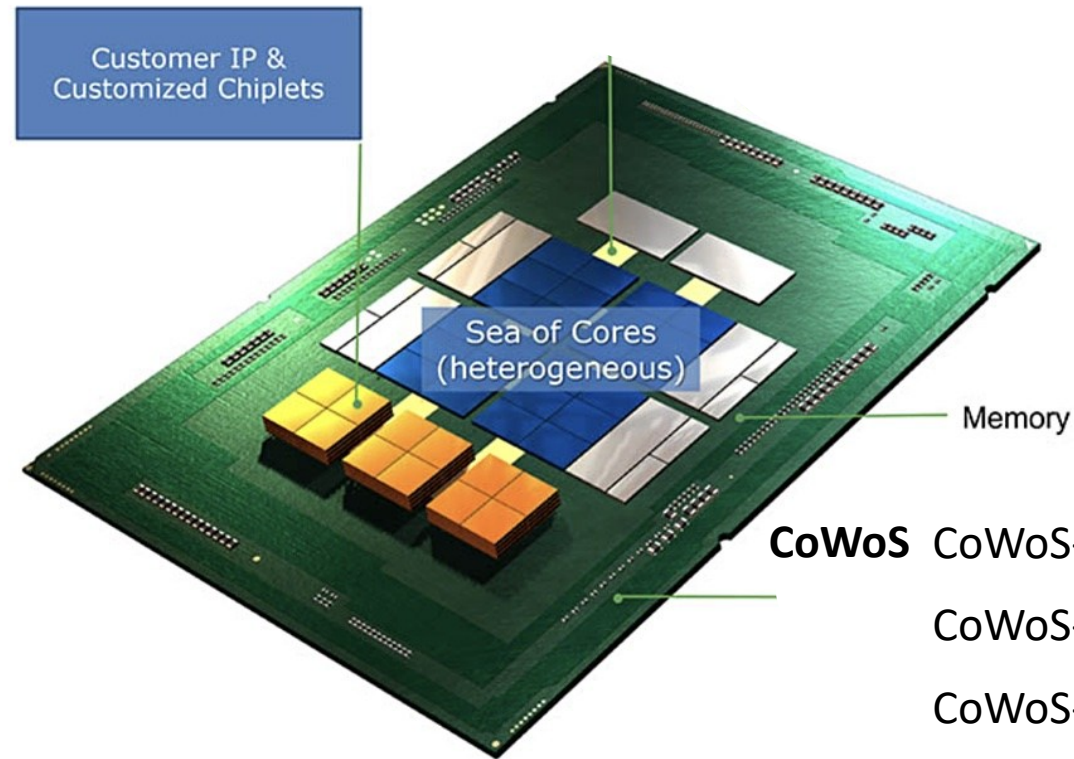
AI HPC Chiplet



- ① HBM3e/4 ② Interposer ③ Substrate ④ AI Acc IO Die
⑤ AI Accelerator Die ⑥ CPU Die ⑦ CPU IO Die

Foundation of Chiplet

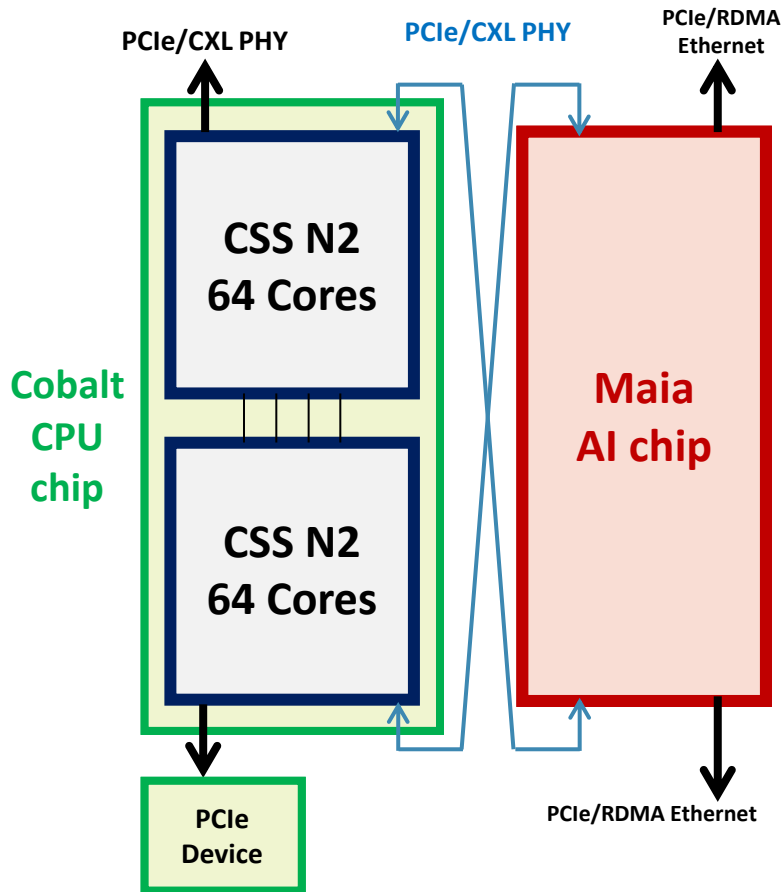
UCle



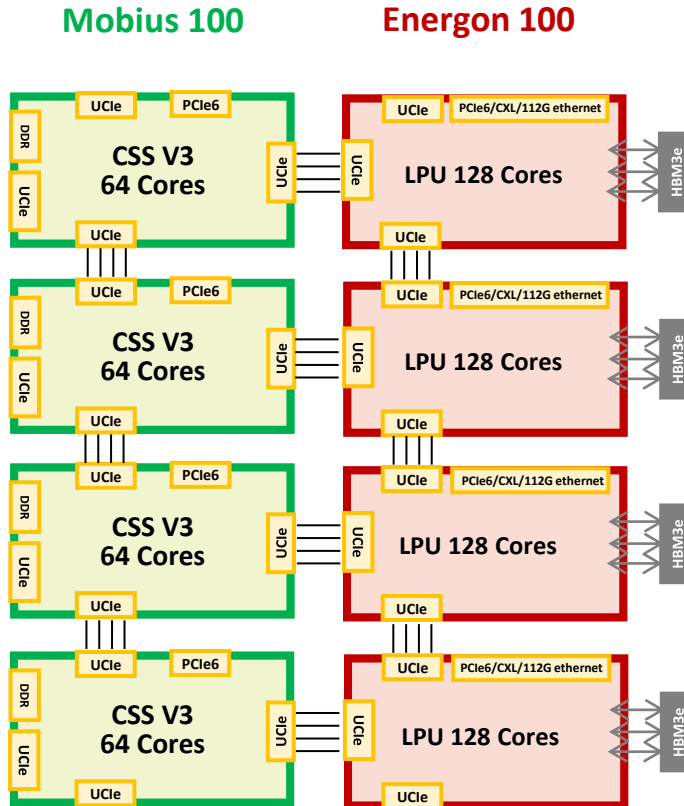
CoWoS CoWoS-S : 3.3x reticle (2831)
CoWoS-R : 4x reticle (3432)
CoWoS-L : 6x reticle (5148)

AI HPC Server Chiplet Roadmap

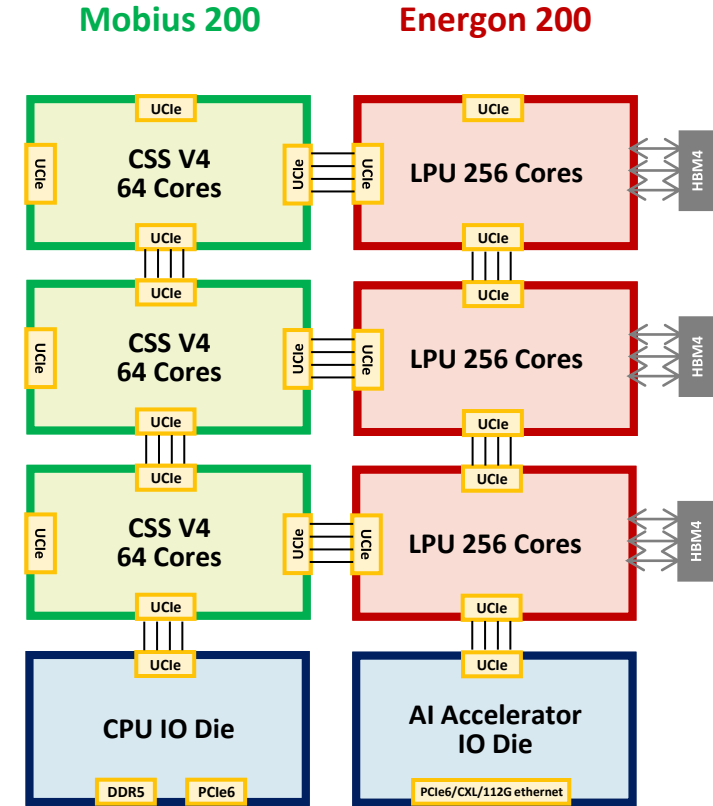
Gen0. SoC



Gen1. UCle/CoWoS

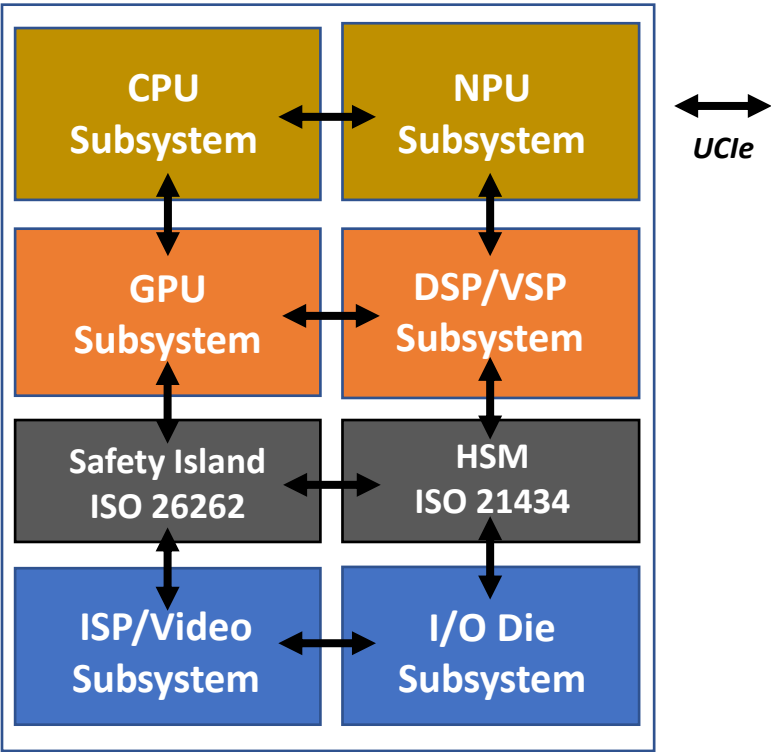
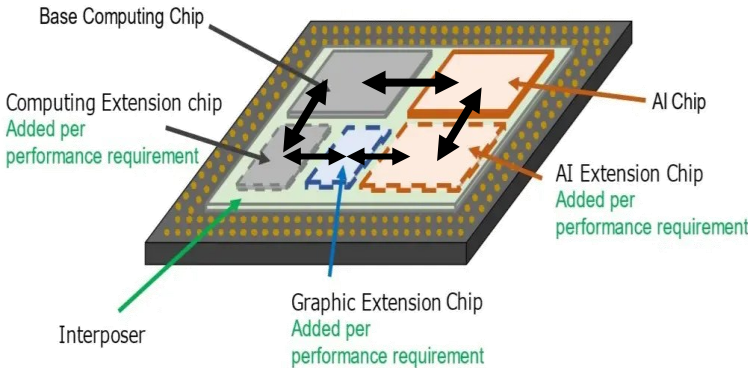
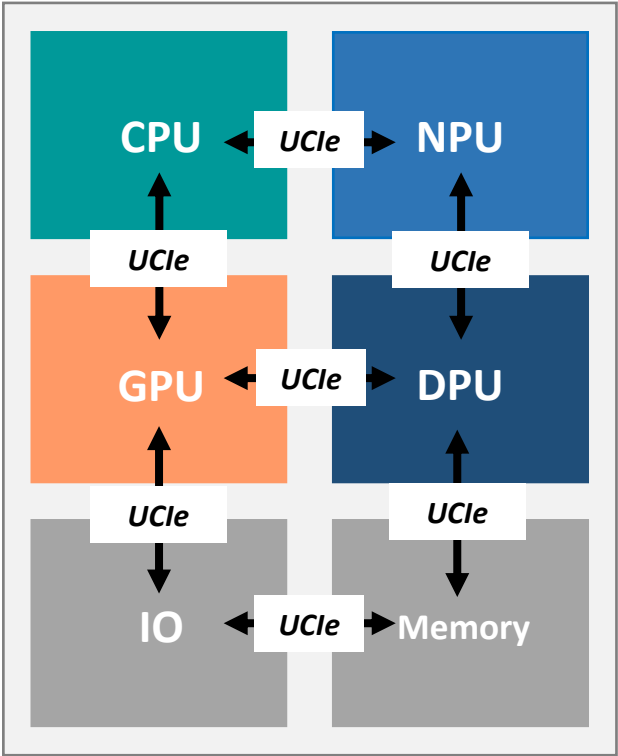


Gen2. UCle/CoWoS/IO Die

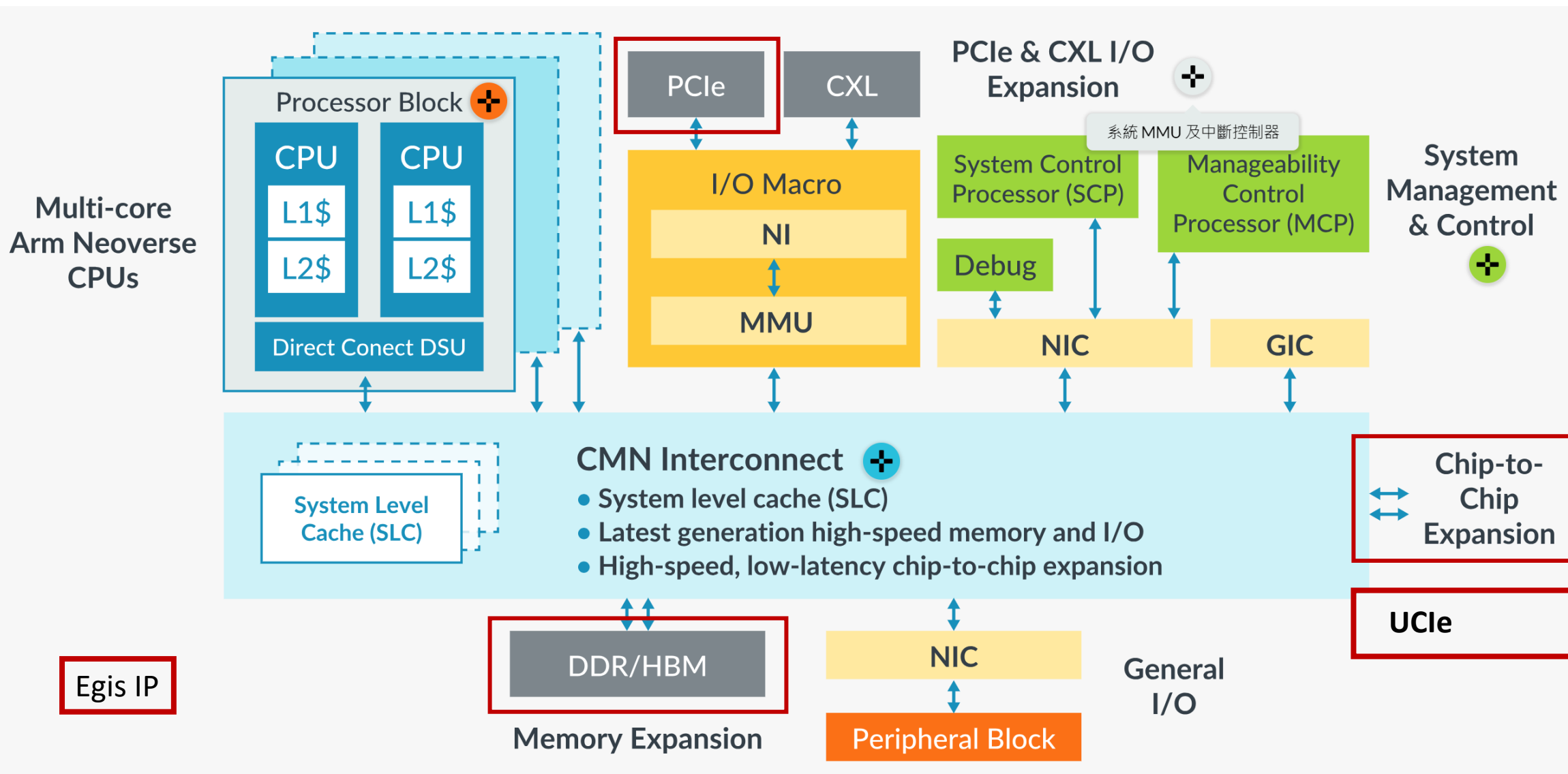


Chiplet in AI HPC Server / Automotive / Drone / Robotics

AI HPC Server

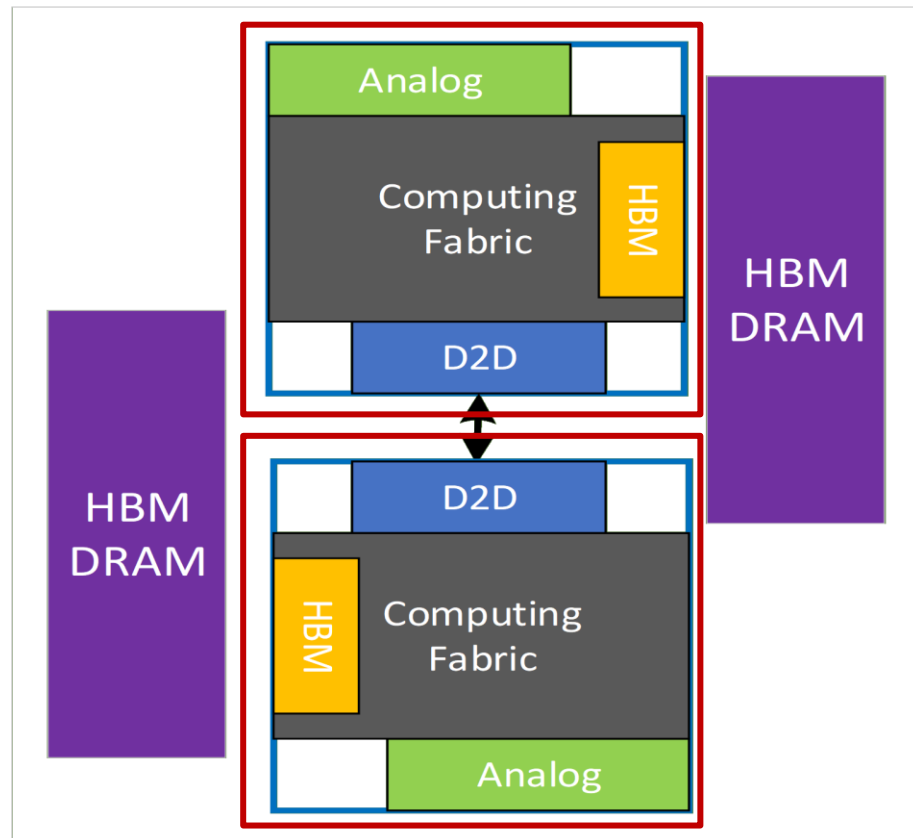


Egis IP & Arm CSS V3

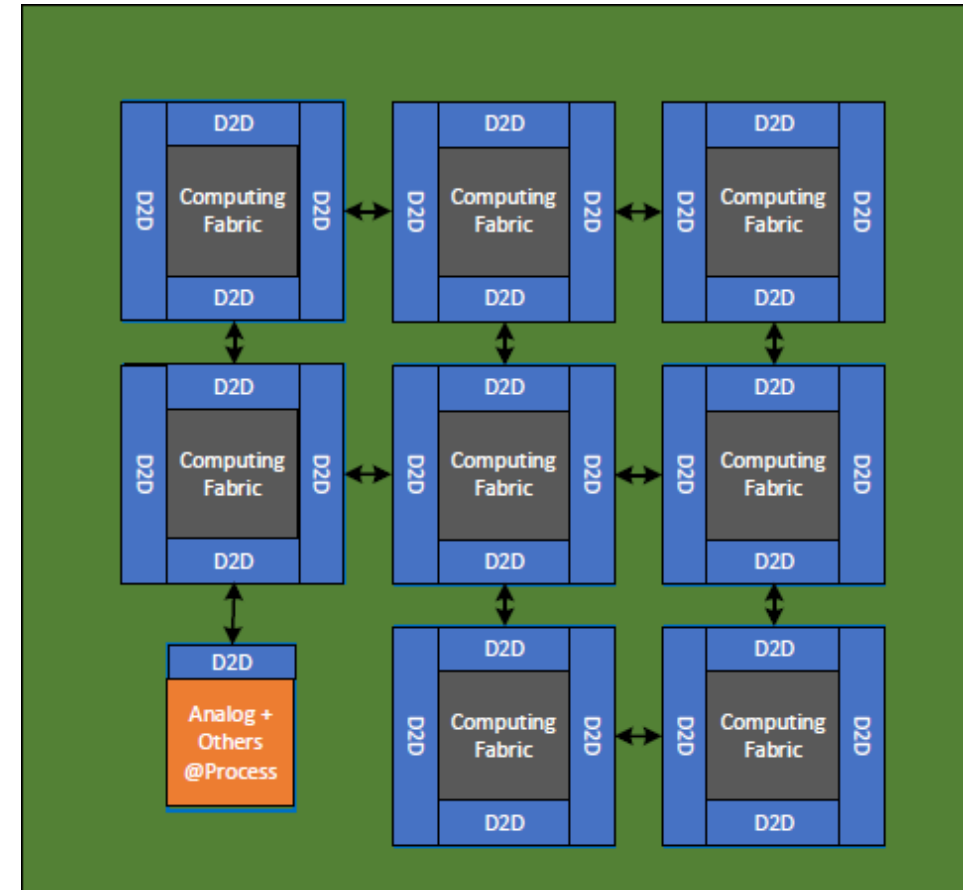


UCIe Advanced Package - CoWoS

- 5/4nm (8 channel, 48Tx/48Rx per channel)
 - 12.3Tbps data rate @16G per bit per PHY
 - Latency 3~4ns



- 3nm (8 channel, 64Tx/64Rx per channel)
 - 16.38Tbps data rate @16G per bit per PHY
 - Latency 3~4ns



Arm Total Design Partners

Arm Total Design – Ecosystem Doubles in One Year

FOUNDRY



DESIGN SERVICES & OEMs



3RD PARTY IP, EDA, & FIRMWARE



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NEOVERSE

Arm Total Design Partners

ATD Partners Provide Chiplets and Value-added Services



+ Neoverse CSS V3 Chiplet for AI on Samsung Foundry



ALPHAWAVE SEMI

+ Neoverse N3 Chiplet for Networking / data centers on TSMC



+ Neoverse CSS V3 Chiplet for Edge Servers on TSMC



FARADAY

+ Neoverse CSS V3 Test chip on Intel Foundry



+ Neoverse N2 Chiplet for DPUs on TSMC



NOVATEK

+ Neoverse N2 Test chip for AI on TSMC



REALTEK

+ Neoverse CSS N- Series Networking & Edge Chiplet

socionext™

+ Neoverse CSS V3 Chiplet on TSMC

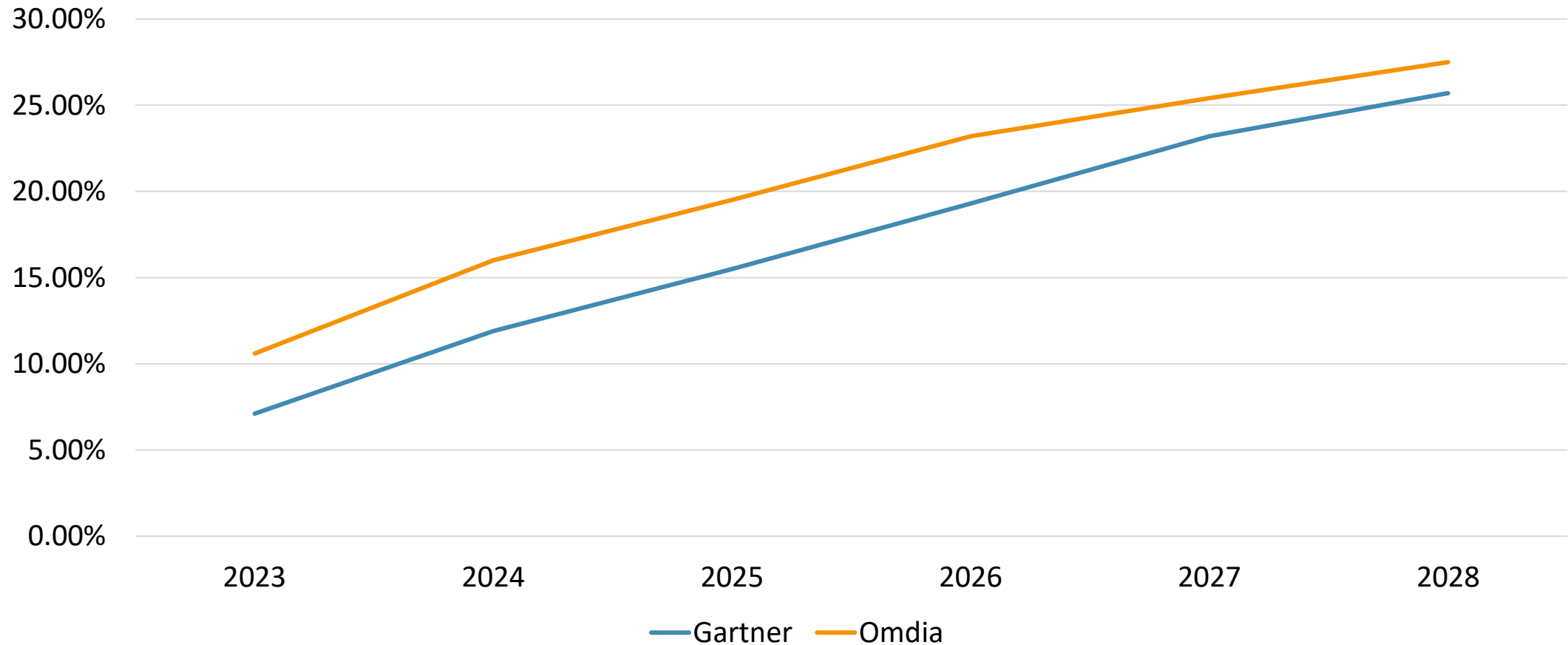
Arm Total Design Partners' Deep Silicon Expertise & Collaboration Drives Faster TTM for Chiplets

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arm
NEOVERSE

Growth Momentum of ARM in the Server Market

Financial Forecast Analysis: Arm targets to achieve a 16%-20% market share in the server market by 2025.



Global ARM-based Server Market

TABLE – GLOBAL ARM-BASED SERVERS MARKET, BY APPLICATION, 2022-2031 (USD MILLION)

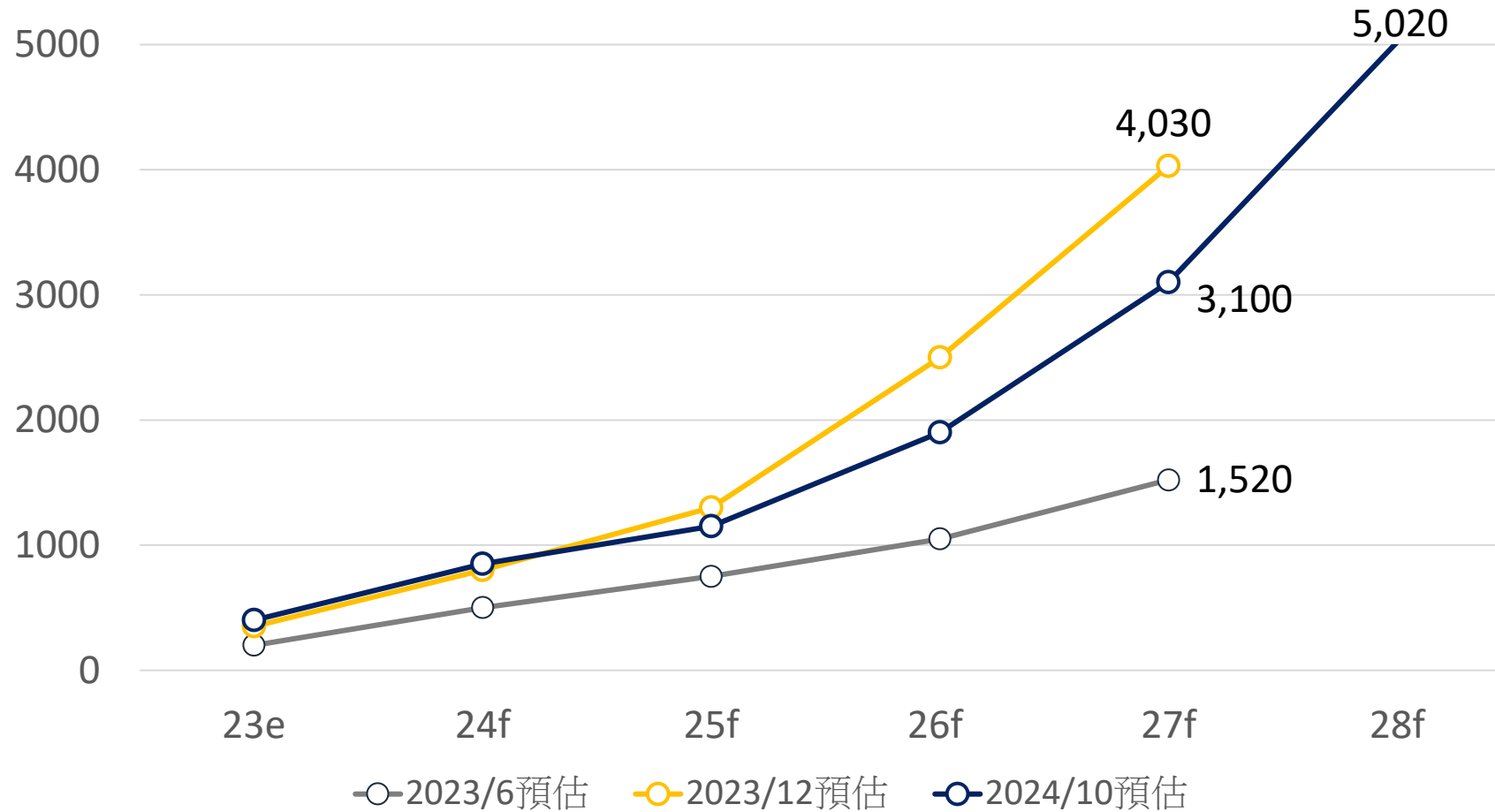
Application	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	CAGR (2024-31)
Data Centers	2342.8	2621.2	2966.6	3377.6	3866.2	4453.0	5151.1	5989.9	6997.0	8214.9	15.66%
Cloud Computing	1007.7	1097.7	1198.6	1313.8	1444.8	1595.0	1765.5	1960.7	2183.7	2439.6	10.69%
HPC	831.9	917.0	1013.7	1125.6	1254.9	1405.4	1579.1	1781.4	2016.4	2291.1	12.36%
Web Hosting	586.9	643.3	707.0	780.3	864.5	961.8	1073.4	1202.3	1351.0	1523.3	11.59%
Enterprise IT	520.0	565.2	615.9	673.7	739.4	814.6	899.9	997.3	1108.4	1235.6	10.46%
Telecommunications	506.1	556.2	613.1	678.7	754.2	841.9	942.7	1059.7	1195.0	1352.6	11.97%
Retail/ E-commerce	397.6	436.1	484.9	541.8	608.0	685.7	776.1	882.1	1006.3	1152.6	13.17%
Others	1108.5	1185.1	1277.6	1381.8	1498.9	1631.2	1779.1	1945.8	2132.9	2343.8	9.06%
Total	7301.5	8021.8	8877.3	9873.3	11031.0	12388.7	13966.7	15819.2	17990.6	20553.5	12.74%

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AI加速器規模快速成長

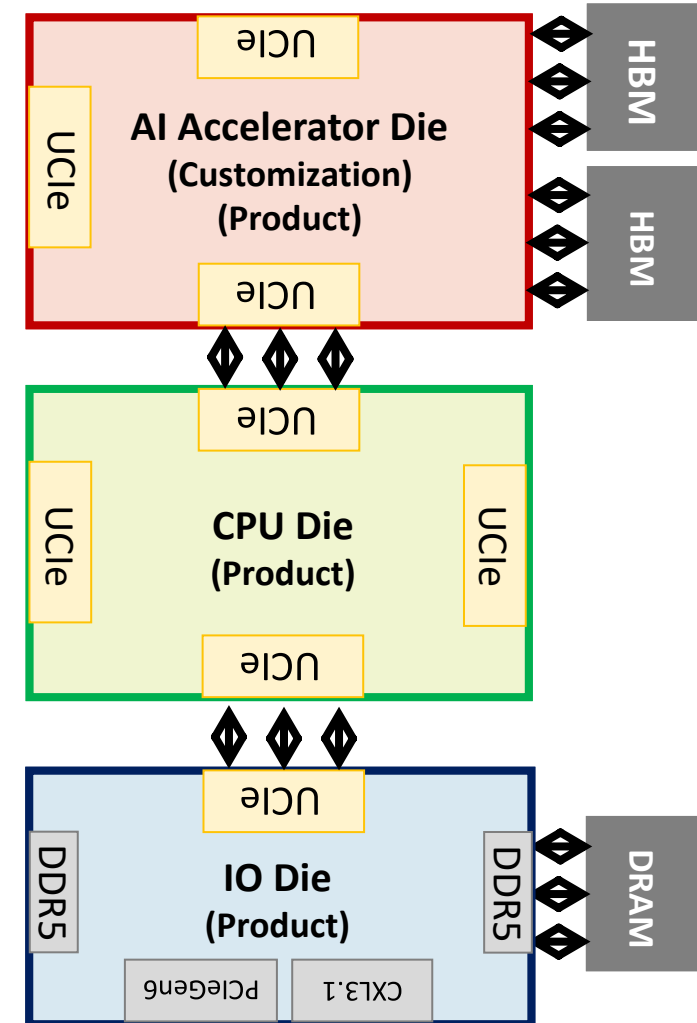
2023~2028年全球資料中心AI加速器市場規模預估



資料來源: AMD、TNP、The Next Platform

Business Strategy & Core Competency

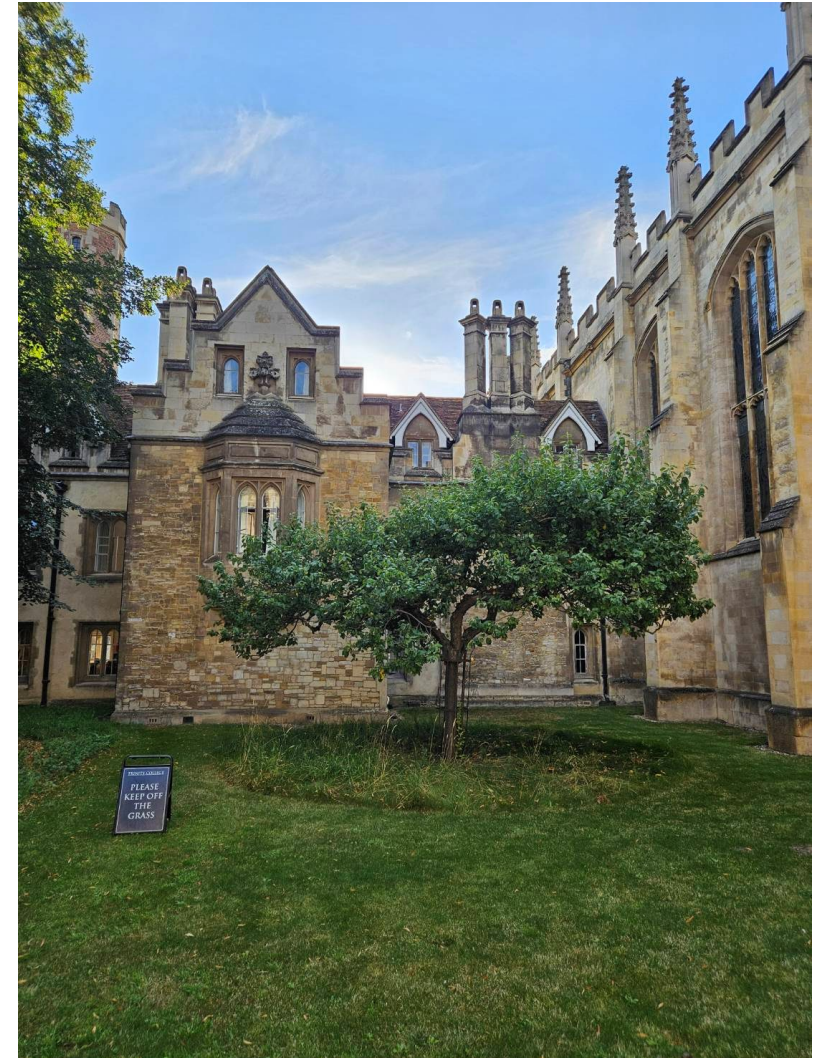
- IP : UCle (D2D), DDR5, PCIeGen6
- ASIC Design Service :
 - Arm CSS V3 (3/4nm)
 - AI Accelerator Die Customization
 - CoWoS Turnkey Solution
 - HBM Base Die Design Service
- Chip : CPU chip, I/O chip, AI Accelerator chip



Go with Winner **arm**

**If I have seen further than others,
it is by standing on the shoulders
of Giants.**

**and Go further on the way of
Success**



Thanks

